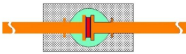
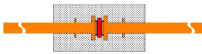


		PCN Notification Document #: The Open Junction(OJ) Diode series is changed to Glassivation Passivation Process(GPP) structure PCN Issue Date: 2024/12/25 PCN#: 20241225001	
变更内容： Title of Change:		OJ系列的产品变更为GPP结构的变更 The Open Junction(OJ) Diode series is changed to Glassivation Passivation Process(GPP) structure PCN	
首议首购日期： Proposed first ship date :		/	
联系方式： Contact Information:		请联系丽正销售办公室 或 访问www.rectron.com 取得最新信息。 Please contact Rectron Sales Office or visit www.rectron.com for nearest contact information.	
样品： Samples:		请联系丽正销售办公室 或 访问www.rectron.com 取得最新信息。 Please contact Rectron Sales Office or visit www.rectron.com for nearest contact information. 样品交付时间将根据客户要求日期、样品数量和特殊包装/标签要求而定。 Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
其他可靠性数据： Additional Reliability Data:		请联系丽正销售办公室 或 访问www.rectron.com 取得最新信息。 Please contact Rectron Sales Office or visit www.rectron.com for nearest contact information.	
通知类型： Type of notification:		这是发给客户的产品/过程变更通知。 This is a Product/Process Change Notification (FPCN) sent to customers.	
变更部分说明： Change Part Identification:		4M变更。 4M Change.	
变更类别： Change Category:		☒ 材料 Material ☐ 设备/工具 Machine/Tooling ☒ 方法 Method ☐ 生产环境 Manufacture site ☐ 人 Man	
变更子类别： Change Sub-Category(s):		1.OJ DICE 变更为 GPP DICE Change OJ DICE to GPP DICE 2.取消对应 OJ DICE的酸洗制程和上硅胶工序 Cancel the etching process and silicone coating process corresponding to OJ DICE	
前一版本的最后订购日期： Last order date for previous version		2024/12/31	
描述与目的： Description and Purpose:		1.由于该OJ工艺(酸洗)对环境的污染，政府对我司审查后通知要求禁止该工艺。 Due to the environmental pollution caused by the OJ process (etching), the government notified our company to ban the process after reviewing it. 2.GPP Dice具有比OJ Dice更好的抗外力能力和可靠性。 GPP process has better HiRel ability to cope with electrical and temp stress than the lower grade OJ process. For example, only GPP is used in autograde applications due to higher reliability.	
内容 Point:	变更 Change	更改前 Before	更改后 After
原物料 Raw materials	晶粒类型 DICE type	O/J晶粒 O/J DICE	GPP晶粒 GPP DICE
	白胶 silicone	白胶 silicone	Infused glass passivation
工艺流程 Process flow	取消工序 Cancel the corresponding process flow	焊接→酸洗→上白胶→成型 Soldering → etching → silicone coating → molding	焊接→成型 Soldering → molding
内部结构 Internal structure	图示 Graphical representation		
电性总结： Electrical Characteristic Summary:		电性无影响/No influence on any datasheet limits	
变更的潜在风险： Possible risks after the change :		低风险/Low risk	
相应的风险评估(可靠性) Corresponding risk assessment (reliability) :		通过可靠性评估试验,可根据要求提供HiRel测试报告 Pass the reliability evaluation test,HiRel test reports available upon requests	

影响料号： List of Affected Parts:		如下所示： As follows:	
料号 Part Number	建议新料号 Suggest New Part Number	其他 Addition	备注 Mark
FFM1800W -T	FFM1800W -T		
FFM1800W -W	FFM1800W -W		
FM1500W -T	FM1500W -T		
FM1500W -T-S-ABB	FM1500W -T-S-ABB		
FM2000W -T	FM2000W -T		
FM2000W -W	FM2000W -W		
FM2500W -W	FM2500W -W		
FFM1600W -T	FFM1600W -T		
FFM1600W -W	FFM1600W -W		
R1500F -T	R1500F -T		
R1800F -B	R1800F -B		
R1800F -T	R1800F -T		
R2000F -F	R2000F -F		
R2000F -T	R2000F -T		
R3000F -B	R3000F -B		
R3000F -B-S-R01	R3000F -B-S-R01		
R4000F -B	R4000F -B		
R5000F -B	R5000F -B		
R3000F -T	R3000F -T		
R4000F -T	R4000F -T		
R5000F -T	R5000F -T		
FRS1JW -W-MA1	FRS1JW -W-MA1		
HFM102W -W	HFM102W -W		
HFM103W -W	HFM103W -W		
HFM105W -T	HFM105W -T		
HFM105W -W	HFM105W -W		
HFM106W -W	FM106W -W		
R1800 -T	R1800 -T		
R2500F -T	R2500F -T		
R3000 -B	R3000 -B		
R4000 -T-S-P50	R4000 -T-S-P50		
R3000 -F	R3000 -F		
R5000 -F	R5000 -F		
R2000 -B	R2000 -B		
R2000 -T	R2000 -T		
R3000 -T	R3000 -T		
R3000 -T-JB1	R3000 -T-JB1		
R4000 -T	R4000 -T		
R5000 -B	R5000 -B		

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